



H2N4126

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The H2N4126 is designed for general purpose switching and amplifier applications.

Features

- Complementary to H2N4124
- High Power PT : 625mW at 25°C
- High DC Current Gain hFE : 120-360 at IC=2mA



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCB0 Collector to Base Voltage -25 V
 VCEO Collector to Emitter Voltage -25 V
 VEBO Emitter to Base Voltage -4 V
 IC Collector Current -200 mA

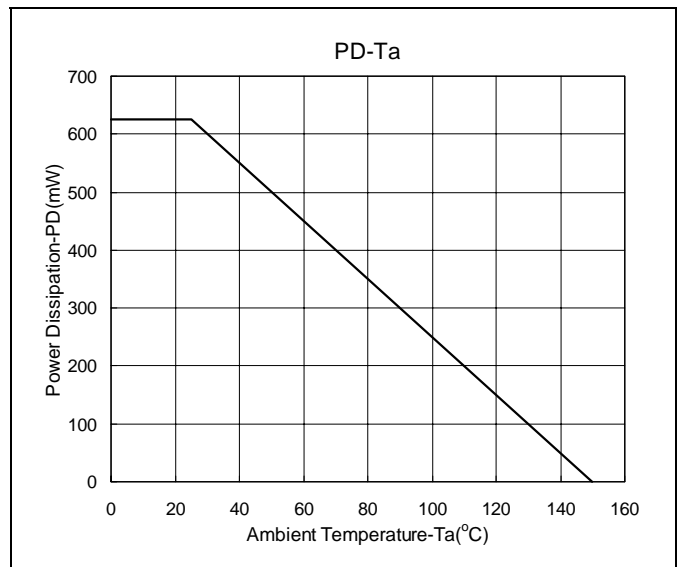
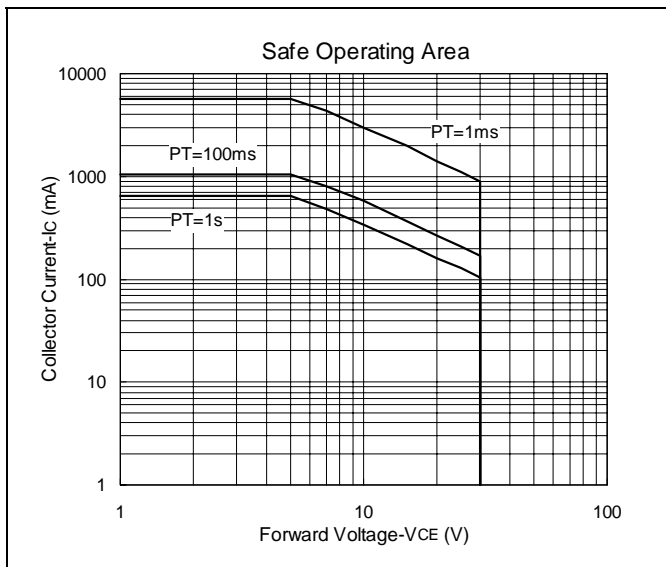
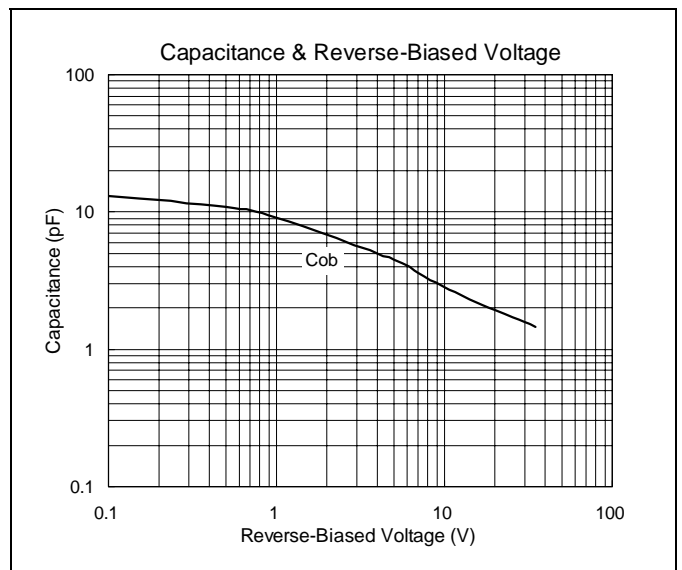
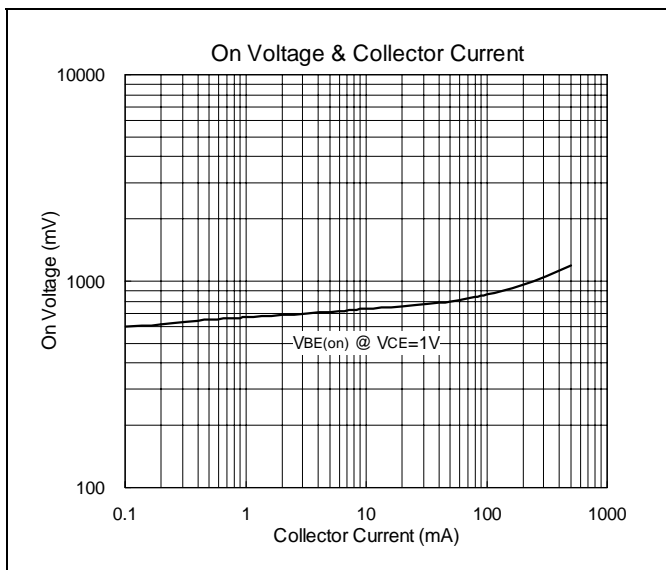
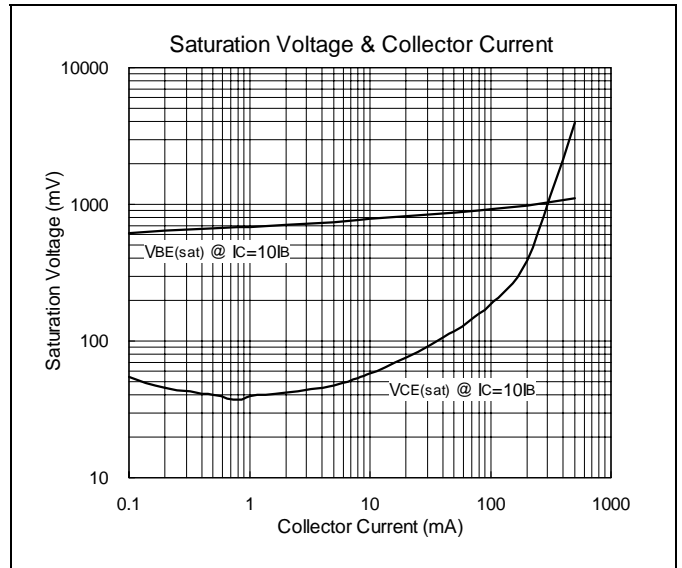
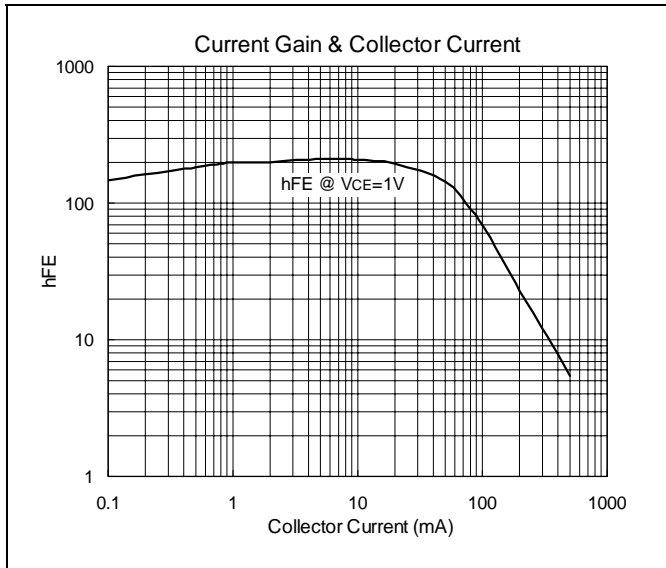
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-25	-	-	V	IC=-10uA, IE=0
BVCEO	-25	-	-	V	IC=-1mA, IB=0
BVEBO	-4	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-50	nA	VCB=-20V, IE=0
IEBO	-	-	-50	nA	VBE=-3V, IC=0
*VCE(sat)	-	-	-400	mV	IC=-50mA, IB=-5mA
*VBE(sat)	-	-	-950	mV	IC=-50mA, IB=-5mA
*hFE1	120	-	360		VCE=-1V, IC=-2mA
*hFE2	60	-	-		VCE=-1V, IC=-50mA
fT	250	-	-	MHz	VCE=-20V, IC=-10mA, f=100MHz
Cob	-	-	4.5	pF	VCB=-5V, IE=0, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



Characteristics Curve





TO-92 Dimension

3-Lead TO-92 Plastic Package
 HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Base 3. Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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